

Fig. 1  
(Prior Art)

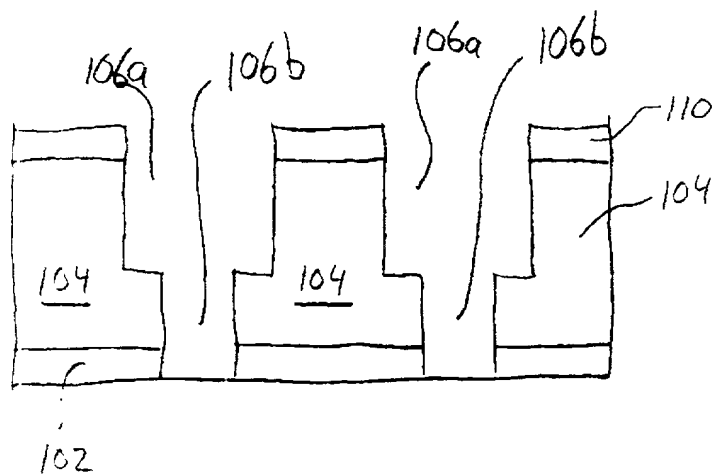


Fig. 2  
(Prior Art)

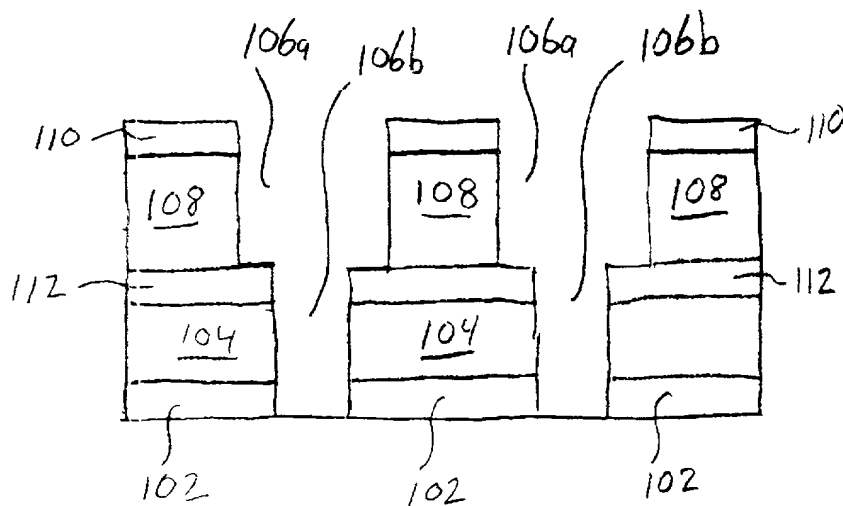
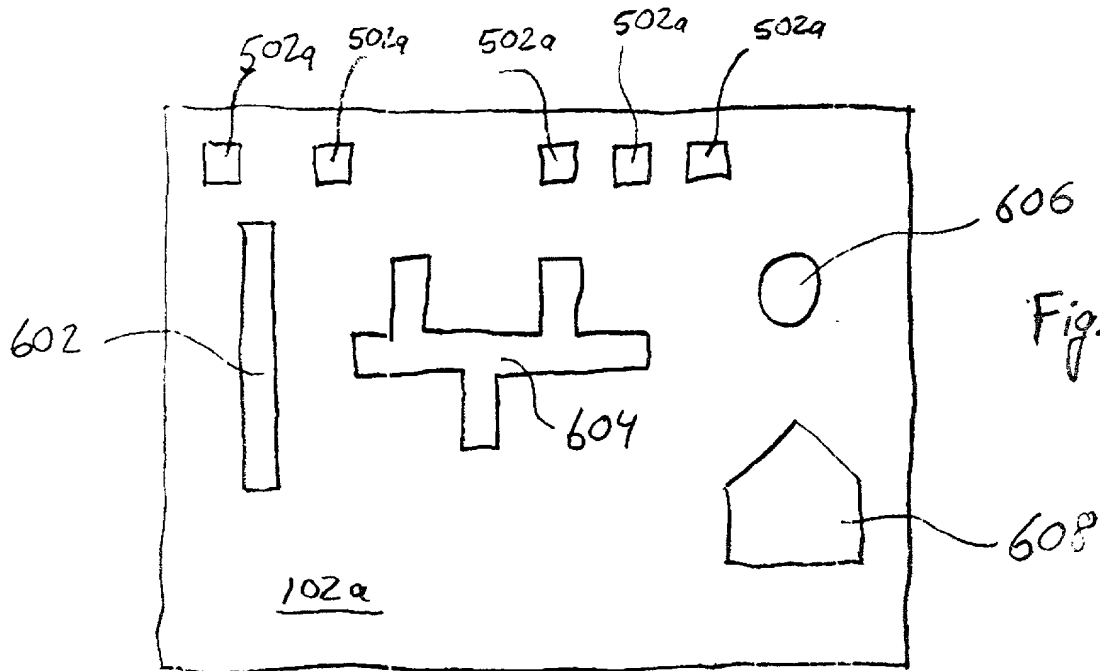
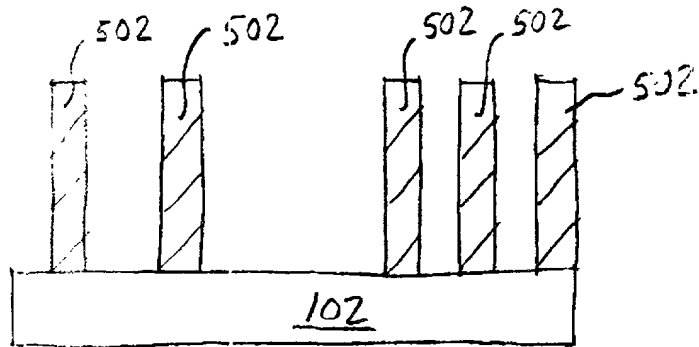
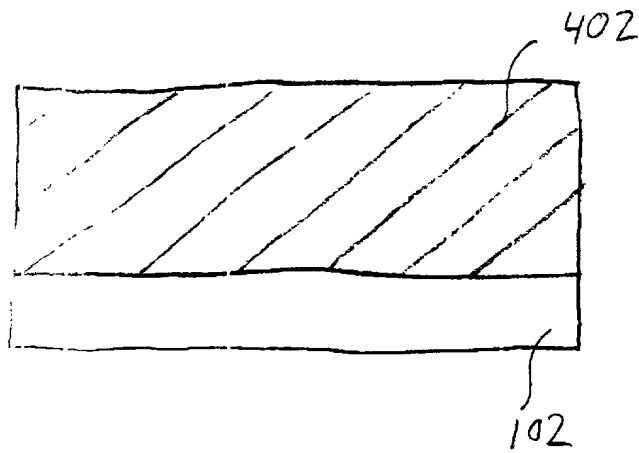


Fig. 3  
(Prior Art)

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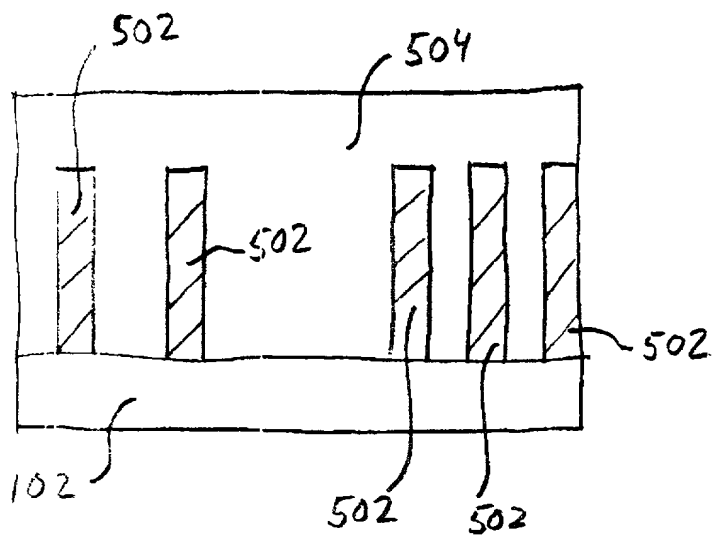


Fig. 7

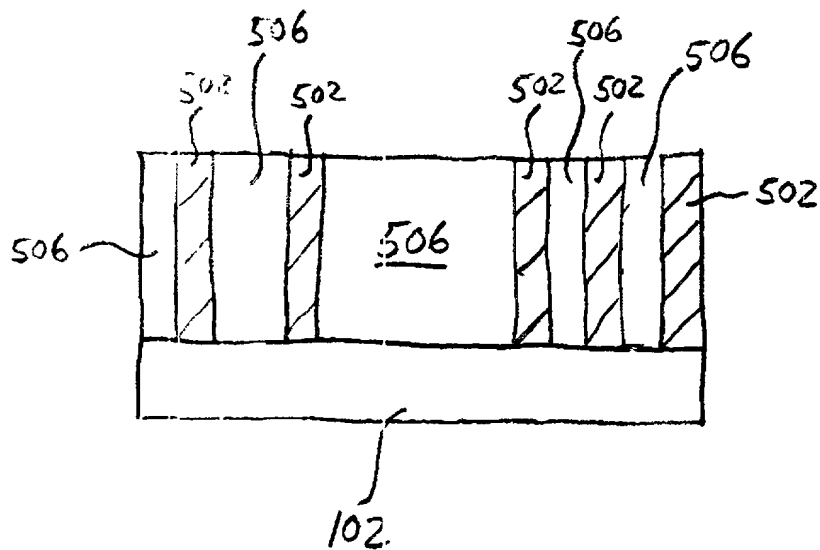
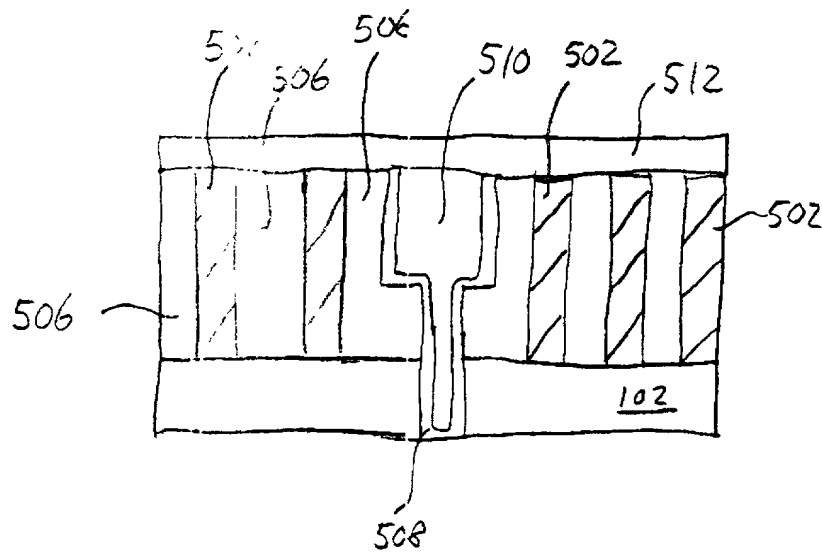
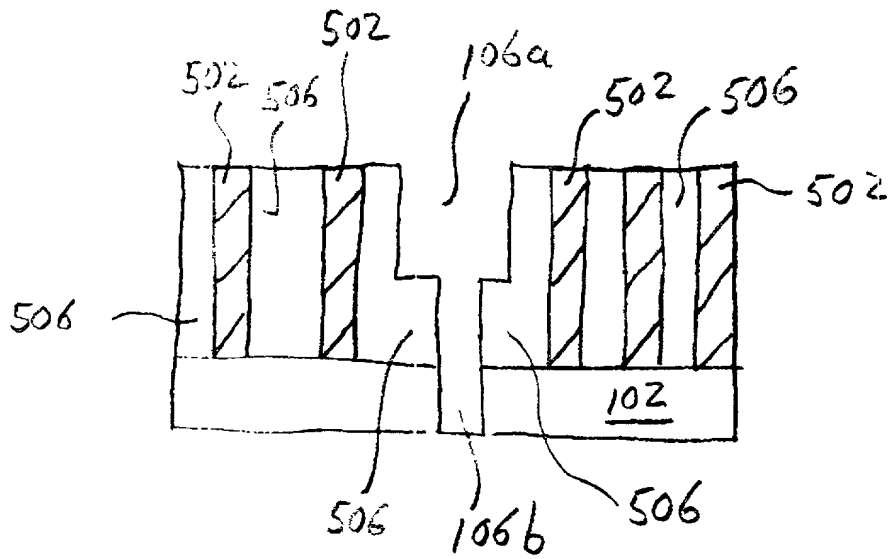


Fig. 8

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Form at least one vertically-oriented non-conductive reinforcing structure on a substrate

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Form a dielectric layer surrounding the reinforcing structure

Fig. 11

Form a first dielectric layer over metal conductors and an intralayer dielectric
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Form a second dielectric layer over the first dielectric layer
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Pattern the second dielectric layer to form reinforcing structures

Form a third dielectric layer over and adjacent the patterned second dielectric

Planarize the third dielectric layer

Form inlaid metal interconnection in the third dielectric layer

Fig. 12